MICROCHIP

Semiconductor Device Type: CH / OT / OTY **(C8X) 006 SOT-23 Matte Tin**

Termination Base Alloy: Copper Alloy (Cu)

Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm
Silica, vitreous	60676-86-0	Mold Compound	57.873	9.838	578,734
Epoxy Resin	Trade Secret	Mold Compound	5.107	0.868	51,075
Phenolic Resin	Trade Secret	Mold Compound	3.403	0.578	34,027
Carbon Black	1333-86-4	Mold Compound	0.206	0.035	2,064
Copper	7440-50-8	Lead Frame	25.738	4.375	257,378
Iron	7439-89-6	Lead Frame	0.633	0.108	6,331
Silver	7440-22-4	Lead Frame	0.513	0.087	5,132
Zinc	7440-66-6	Lead Frame	0.034	0.006	337
Phosphorous	7723-14-0	Lead Frame	0.022	0.004	222
Epoxy resin	Trade Secret	Die Attach	0.132	0.022	1,318
Silicon dioxide	7631-86-9	Die Attach	0.038	0.007	383
Silicon	7440-21-3	Chip (Die)	4.760	0.809	47,600
Copper	7440-50-8	Wire Bond Copper palladium coated (CuPd)	0.305	0.052	3,046
Palladium	7440-05-3	Wire Bond Copper palladium coated (CuPd)	0.005	0.001	54
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	1.230	0.209	12,300
		TOTALS:	**100.000**	**17.000**	**1,000,000**

0.0170 g Total Mass

Package Homogeneous Materials

JEDEC 97 Product Marking and/or Pkg. Labeling e3

(mg) Total	Mold Compound	% ot Total Weight	JEDEC 97
11.32			66.59
	Silica, vitreous	60676-86-0	86.91
	Epoxy Resin	Trade Secret	7.67
	Phenolic Resin	Trade Secret	5.11
	Carbon Black	1333-86-4	0.31
		Total	**100.00**

(mg) Total	Lead Frame	% of Total Weight	JEDEC 97
4.58			26.94
	Copper	7440-50-8	95.54
	Iron	7439-89-6	2.35
	Silver	7440-22-4	1.91
	Zinc	7440-66-6	0.13
	Phosphorous	7723-14-0	0.08
		Total	**100.00**

(mg) Total	Die Attach	% of Total Weight	JEDEC 97
0.03			0.17
	Epoxy resin	Trade Secret	77.50
	Silicon dioxide	7631-86-9	22.50
		Total	**100.00**

Total (mg)	Chip (Die)	% of Total Weight	JEDEC 97
0.81			4.76
	Doped Silicon	7440-21-3	100.00
		Total	**100.00**

(mg) Total	Wire Bond Copper palladium coated (CuPd)	% of Total Weight	JEDEC 97
0.05			0.31
	Copper	7440-50-8	98.25
	Palladium	7440-05-3	1.75
		Total	**100.00**

(mg) Total	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	% of Total Weight	JEDEC 97
0.21			1.23
	Tin	7440-31-5	100.00
		Total	**100.00**

17.000			**100.000**

This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)

Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.

If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.

Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/

The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.

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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table